

(1,27 mm) .050" **LPAF SERIES** 







## **HIGH SPEED LOW PROFILE OPEN PIN FIELD**

4 mm, 4,5 mm

## **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?LPAF

Insulator Material: Black LCP
Contact Material:
Copper Alloy Plating: Au or Šn over 50µ" (1,27 µm) Ni **Current Rating:** 2.2 A per contact (6 contacts powered) Working Voltage: 250 VA0 RoHS Compliant:

Lead-Free Solderable:

## **ALSO** AVAILABLE

- Tin-Lead Solder Charge.
- · Other pins/row and row counts.
- Other Gold plating options. Call Samtec.

Mates with: **LPAM** 



and 5 mm 4 or 6 row standard stack heights .050" (1,27 mm) X .050" (1,27 mm) pitch Dual Beam contact Up to 30 pins per row

LPAM/LPAF 4 mm Stack Height	Rated @ 3dB Insertion Loss*	
Single-Ended Signaling	17 GHz / 34 Gbps	
Differential Pair Signaling	18.5 GHz / 37 Gbps	
*Test board losses de-embedded from performance data.		

Performance data for other stack heights and complete test data available at www.samtec.com?LPAF or contact sig@samtec.com







Solder

crimp

-20, -30 (Per Row)

-03.0 = (3,0 mm) .118"

-03.5 (3,5 mm) .138"

—L = 10µ" (0,25 µm) Gold on contact area Matte Tin on

-04 =Four Rows -06

=Six

Gbps

NO. OF

**ROWS** 

Lead-Free Tin Alloy 95.5% Sn/ 3.8%Ag/ 0.7% Cu

- K = Polyimide film Pick & Place Pad

Α

(2,79) .110

(3,30)

=Tape & Reel

## **MATED HEIGHT**

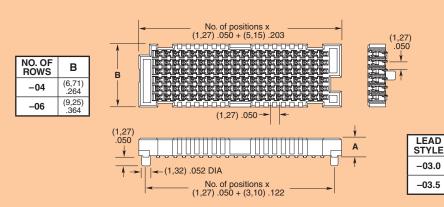


MATED HEIGHT*		
LPAF LEAD	LPAM LEAD STYLE	
STYLE	-01.0	-01.5
-03.0	(4,00) .157	(4,50) .177
-03.5	(4,50) .177	(5,00) .197
*Brossosing conditions will		

Processing conditions will affect mated height.

Note: Patent Pending

Note: Some sizes, styles and options are non-standard, non-returnable.



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM